



US00D729776S

(12) **United States Design Patent**  
**Miyake et al.**

(10) **Patent No.:** **US D729,776 S**

(45) **Date of Patent:** **\*\* May 19, 2015**

(54) **EARPHONE**

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(73) Assignee: **Sony Corporation**, Tokyo (JP)

(\*\*) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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Aug. 29, 2013 (JP) ..... D2013-019943  
Aug. 30, 2013 (CN) ..... 2013 3 0418953

(51) **LOC (10) Cl.** ..... **14-01**

(52) **U.S. Cl.**  
USPC ..... **D14/223**; D14/205

(58) **Field of Classification Search**  
CPC ..... H04R 1/10  
USPC ..... D14/223, 205; D24/174; 181/129, 130,  
181/135; 379/430, 431; 381/380, 381;  
455/90.3, 575.1  
See application file for complete search history.

(56) **References Cited**

**U.S. PATENT DOCUMENTS**

D106,823 S \* 11/1937 Sears ..... D24/174  
D135,674 S \* 5/1943 Williams et al. .... D14/205

(Continued)

**FOREIGN PATENT DOCUMENTS**

JP D1437170 S 4/2012

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(74) *Attorney, Agent, or Firm* — Fishman Stewart Yamaguchi PLLC

(57) **CLAIM**

The ornamental design for an earphone, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of a first embodiment of an earphone showing our new design;  
FIG. 2 is a front elevational view thereof;  
FIG. 3 is a rear elevational view thereof;  
FIG. 4 is a left side elevational view thereof;  
FIG. 5 is a right side elevational view thereof;  
FIG. 6 is a top plan view thereof; and  
FIG. 7 is a bottom plan view thereof.  
FIG. 8 is a cross sectional view thereof along the lines 8-8 and 8'-8' of FIG. 5.

FIG. 9 is a cross sectional view thereof along the lines 9-9 and 9'-9' of FIG. 5.

FIG. 10 is a perspective view of a second embodiment of an earphone showing our new design;  
FIG. 11 is a front elevational view thereof;  
FIG. 12 is a rear elevational view thereof;  
FIG. 13 is a left side elevational view thereof;  
FIG. 14 is a right side elevational view thereof;  
FIG. 15 is a top plan view thereof; and  
FIG. 16 is a bottom plan view thereof.

FIG. 17 is a cross sectional view thereof along the lines 17-17 and 17'-17' of FIG. 14.

FIG. 18 is a cross sectional view thereof along the lines 18-18 and 18'-18' of FIG. 14.

FIG. 19 is a perspective view of a third embodiment of an earphone showing our new design;

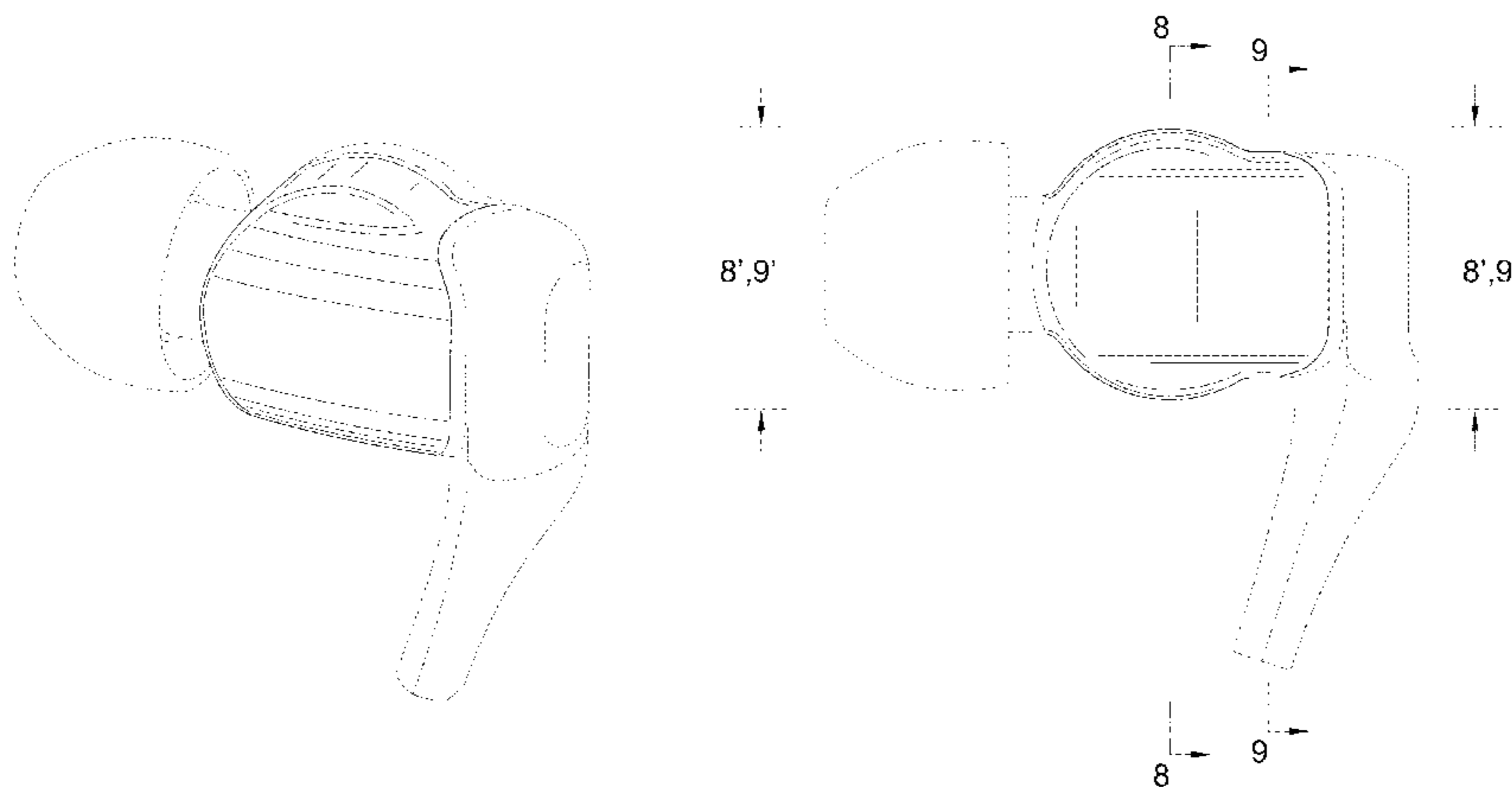
FIG. 20 is a front elevational view thereof;  
FIG. 21 is a rear elevational view thereof;  
FIG. 22 is a left side elevational view thereof;  
FIG. 23 is a right side elevational view thereof;  
FIG. 24 is a top plan view thereof; and  
FIG. 25 is a bottom plan view thereof.

FIG. 26 is a cross sectional view thereof along the lines 26-26 and 26'-26' of FIG. 23; and,

FIG. 27 is a cross sectional view thereof along the lines 27-27 and 27'-27' of FIG. 23.

The broken lines forms no part of the claimed design.

**1 Claim, 18 Drawing Sheets**



(56)

References Cited

U.S. PATENT DOCUMENTS

D206,228 S \* 11/1966 Strzalkawski ..... D24/174  
 D206,718 S \* 1/1967 Barry ..... D24/174  
 D208,784 S \* 10/1967 Sanzone ..... D24/174  
 D468,301 S \* 1/2003 Fushimi ..... D14/223  
 D529,612 S \* 10/2006 Feeley et al. .... D24/174  
 D564,098 S \* 3/2008 Lockenwitz ..... D24/174  
 D564,495 S \* 3/2008 Sasaki ..... D14/205  
 D567,217 S \* 4/2008 Kamo et al. .... D14/205  
 D587,247 S 2/2009 Densho  
 D587,248 S \* 2/2009 Densho ..... D14/223  
 D587,249 S 2/2009 Densho  
 D587,681 S \* 3/2009 Yanai ..... D14/205  
 7,551,748 B2 \* 6/2009 Kamo et al. .... 381/380  
 D598,431 S 8/2009 Densho

D605,636 S \* 12/2009 Yang ..... D14/223  
 D605,769 S \* 12/2009 Sjursen et al. .... D24/174  
 D610,129 S 2/2010 Densho et al.  
 D631,470 S \* 1/2011 Yoneyama et al. .... D14/223  
 D670,274 S 11/2012 Katsumata et al.  
 8,391,533 B2 \* 3/2013 Sim et al. .... 381/380  
 D679,682 S 4/2013 Shimizu et al.  
 D680,102 S \* 4/2013 Chen ..... D14/223  
 D682,257 S 5/2013 Zheng et al.  
 D702,668 S \* 4/2014 Narita et al. .... D14/223  
 D705,757 S \* 5/2014 Yashiro ..... D14/223  
 D707,657 S \* 6/2014 Burt et al. .... D14/223  
 D710,334 S \* 8/2014 Yang ..... D14/223  
 D711,858 S \* 8/2014 Yang ..... D14/223  
 D715,775 S \* 10/2014 Rueskov ..... D14/221  
 D719,550 S \* 12/2014 Yang ..... D14/223  
 2007/0189570 A1 \* 8/2007 Matsuo et al. .... 381/382

\* cited by examiner

FIG.1

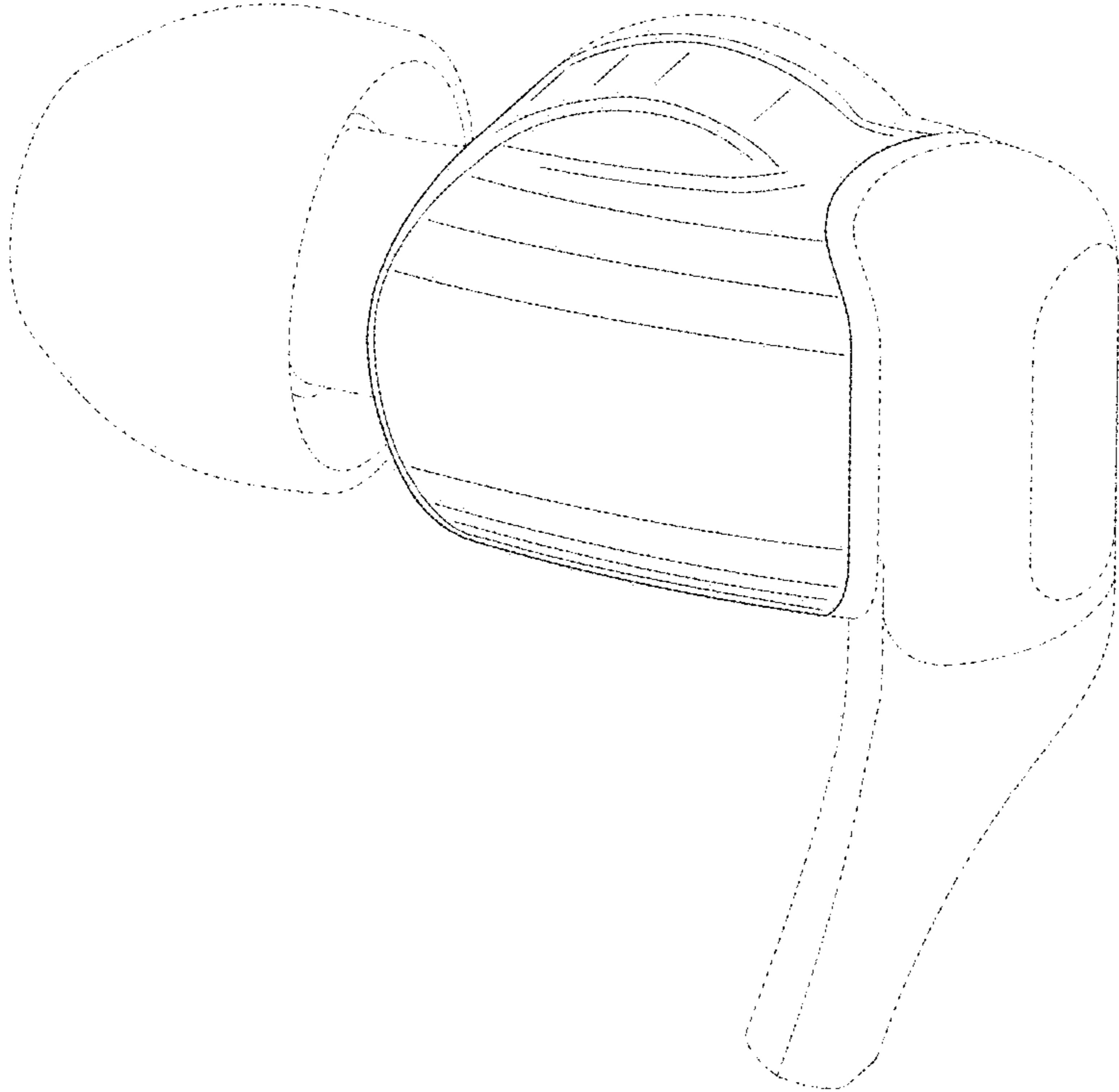


FIG.2

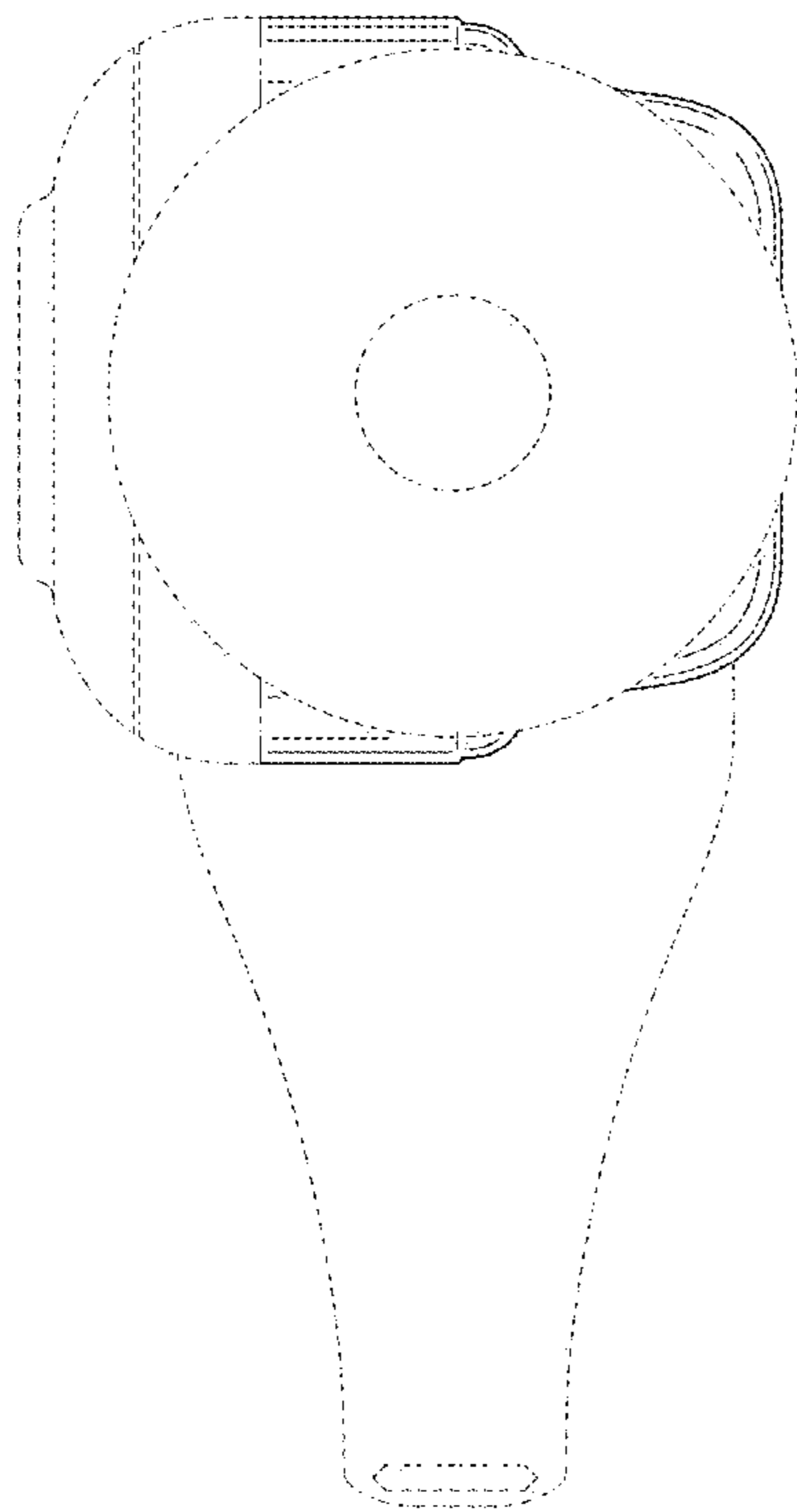


FIG.3

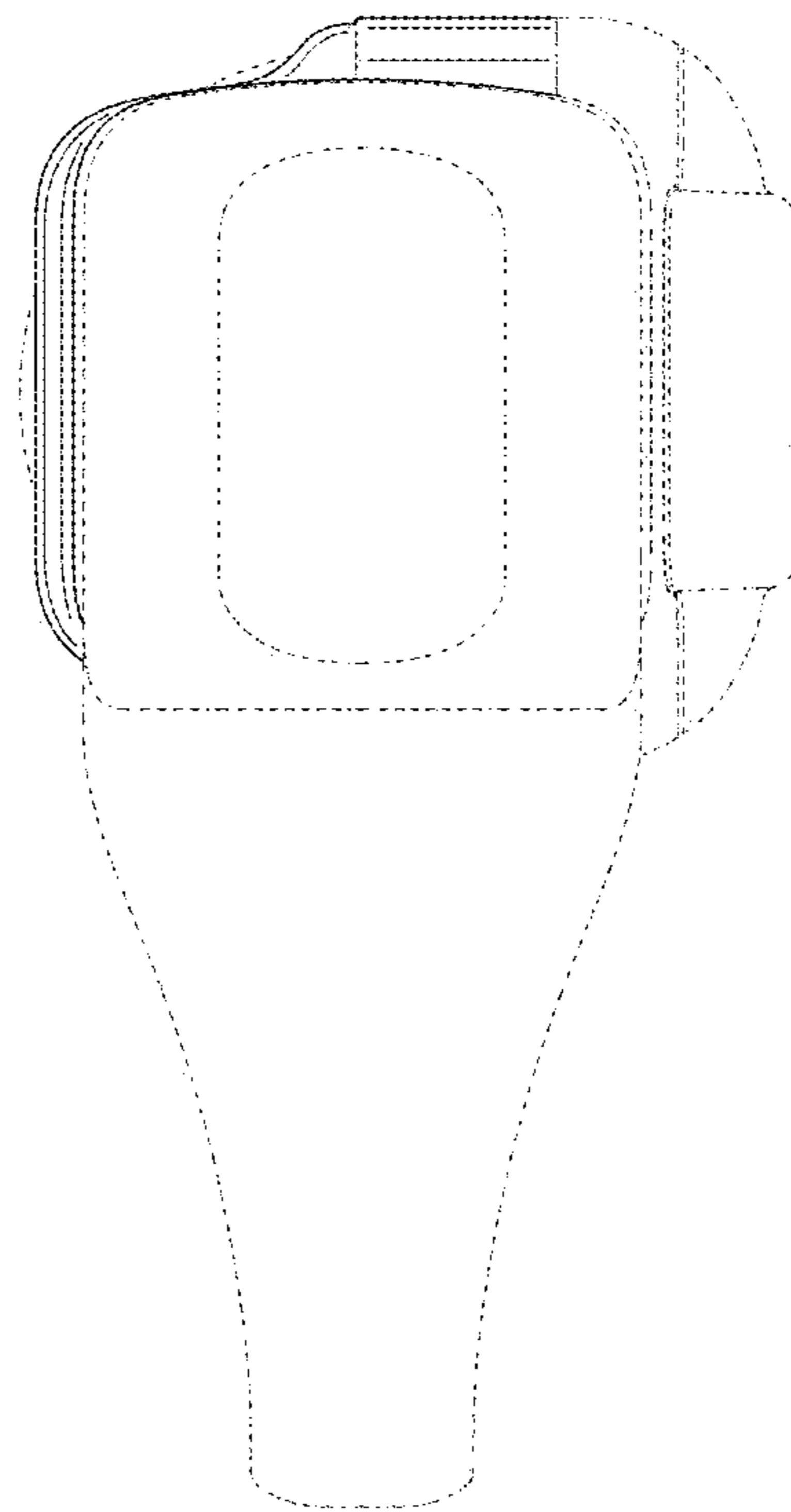


FIG.4

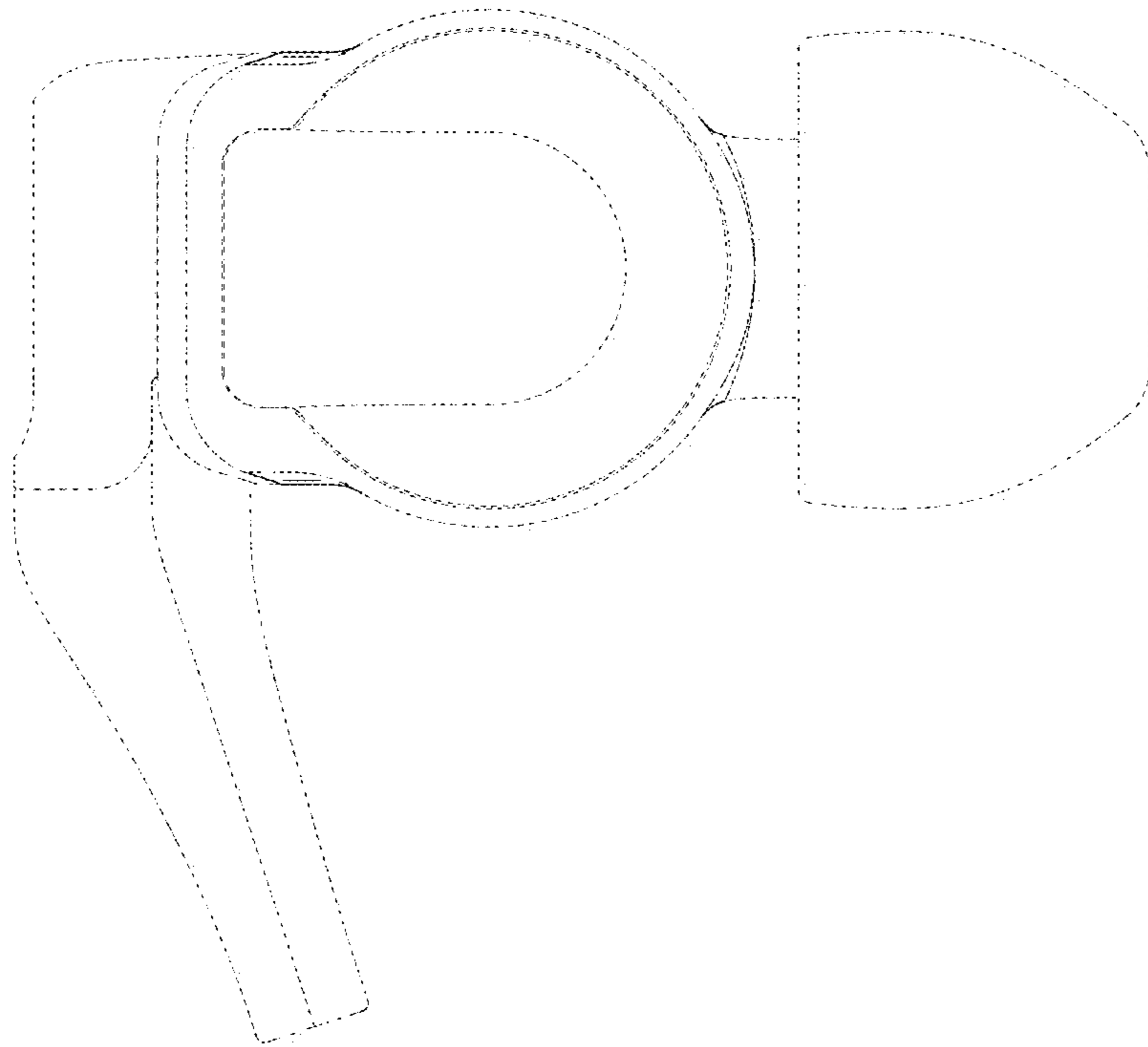


FIG.5

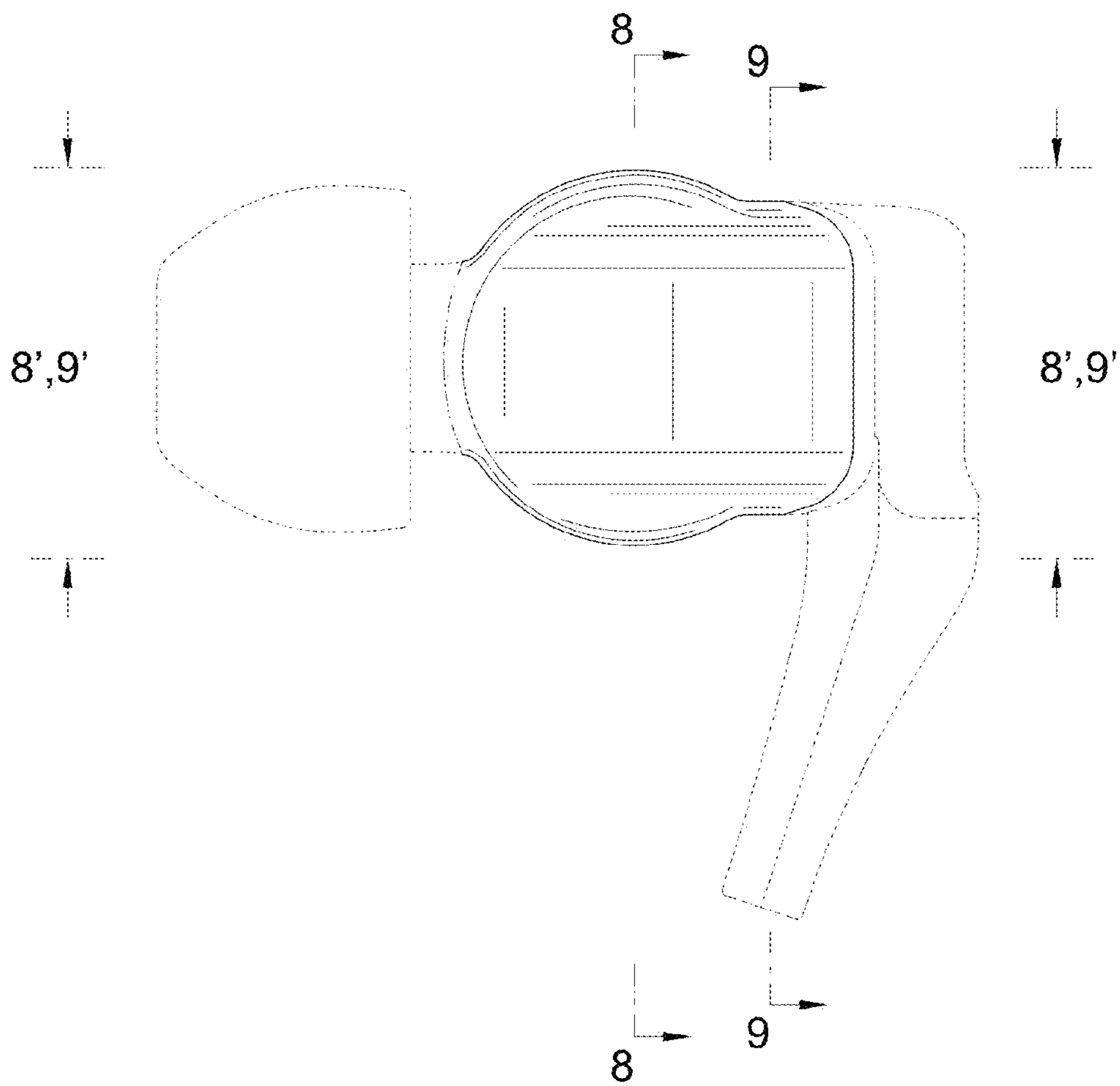


FIG.6

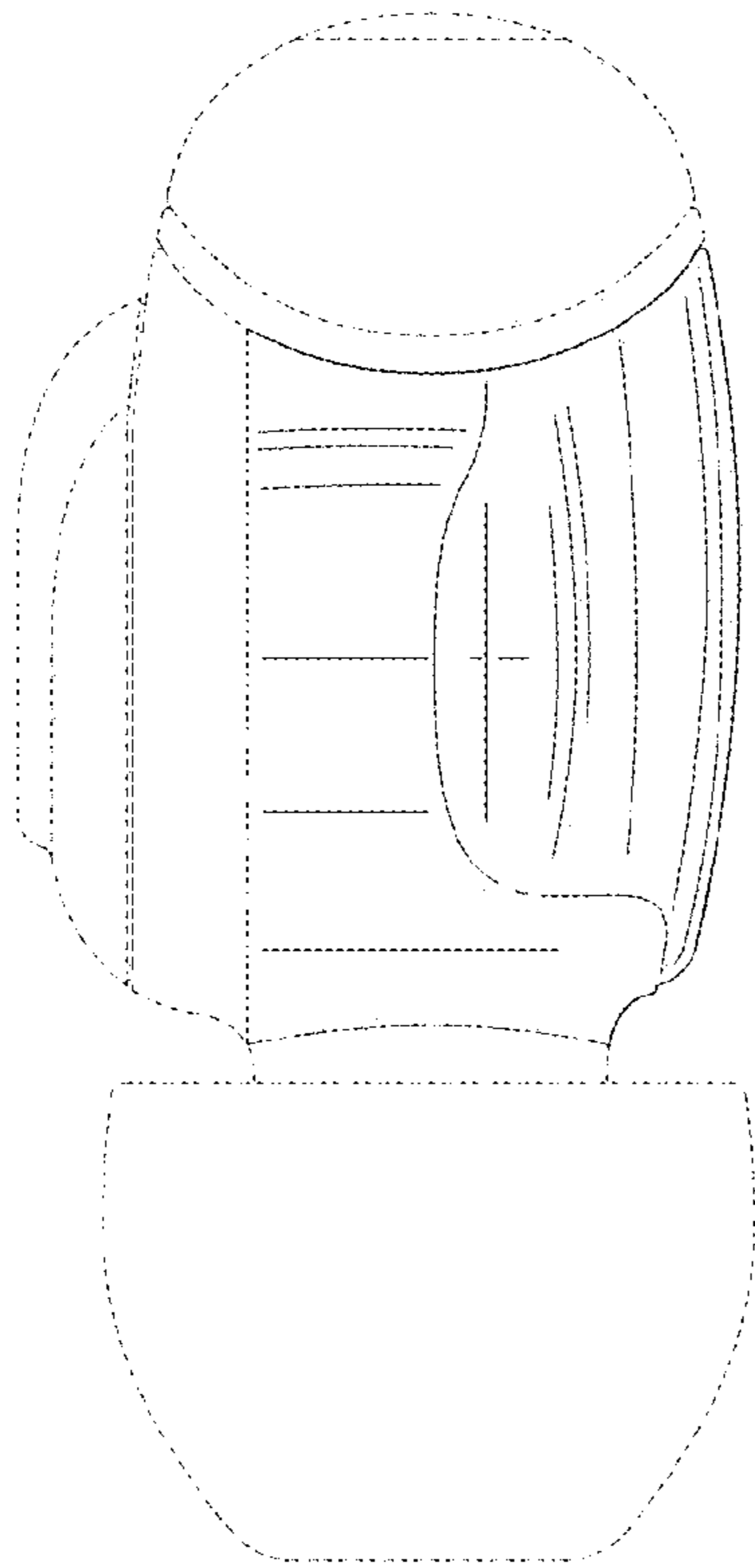


FIG.7

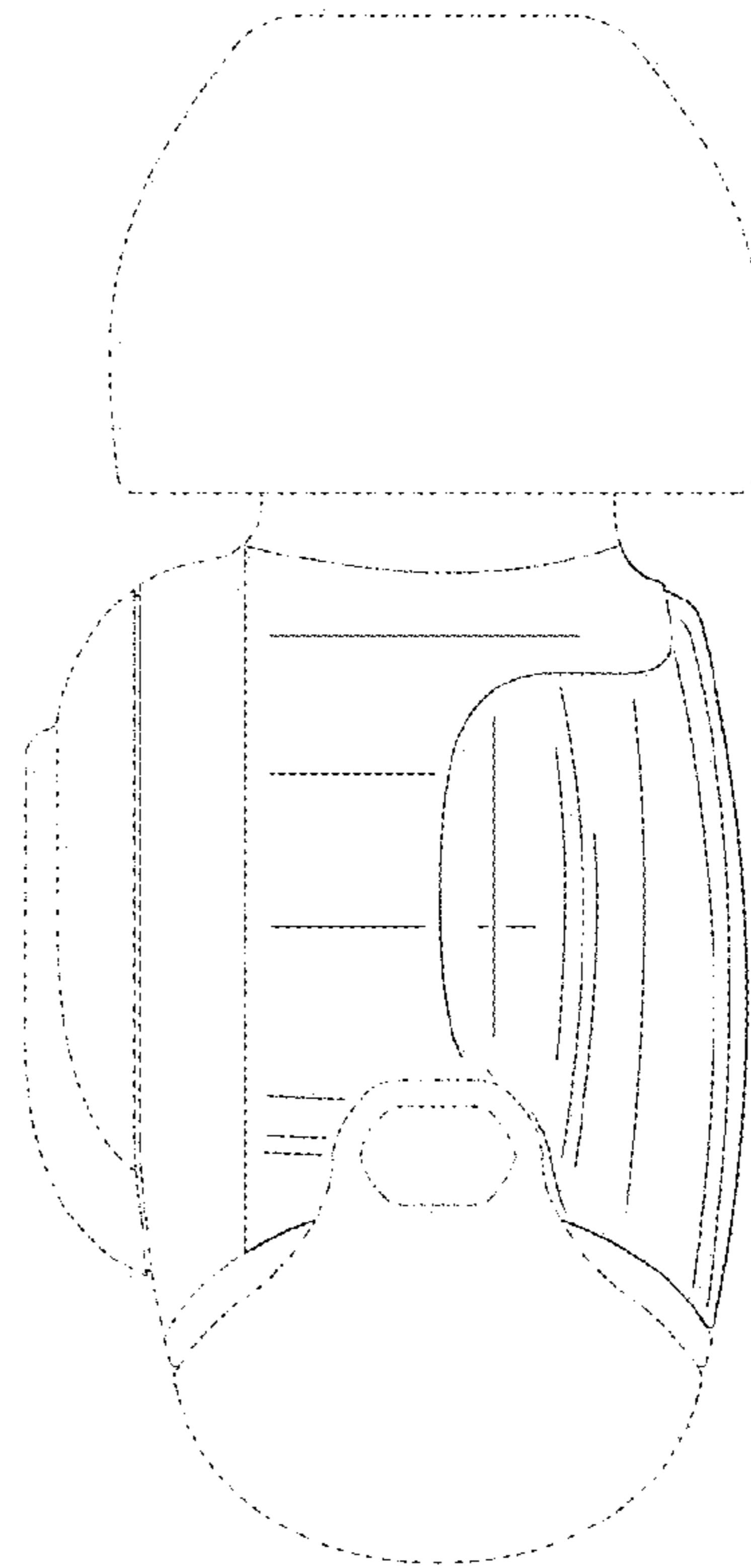


FIG.8

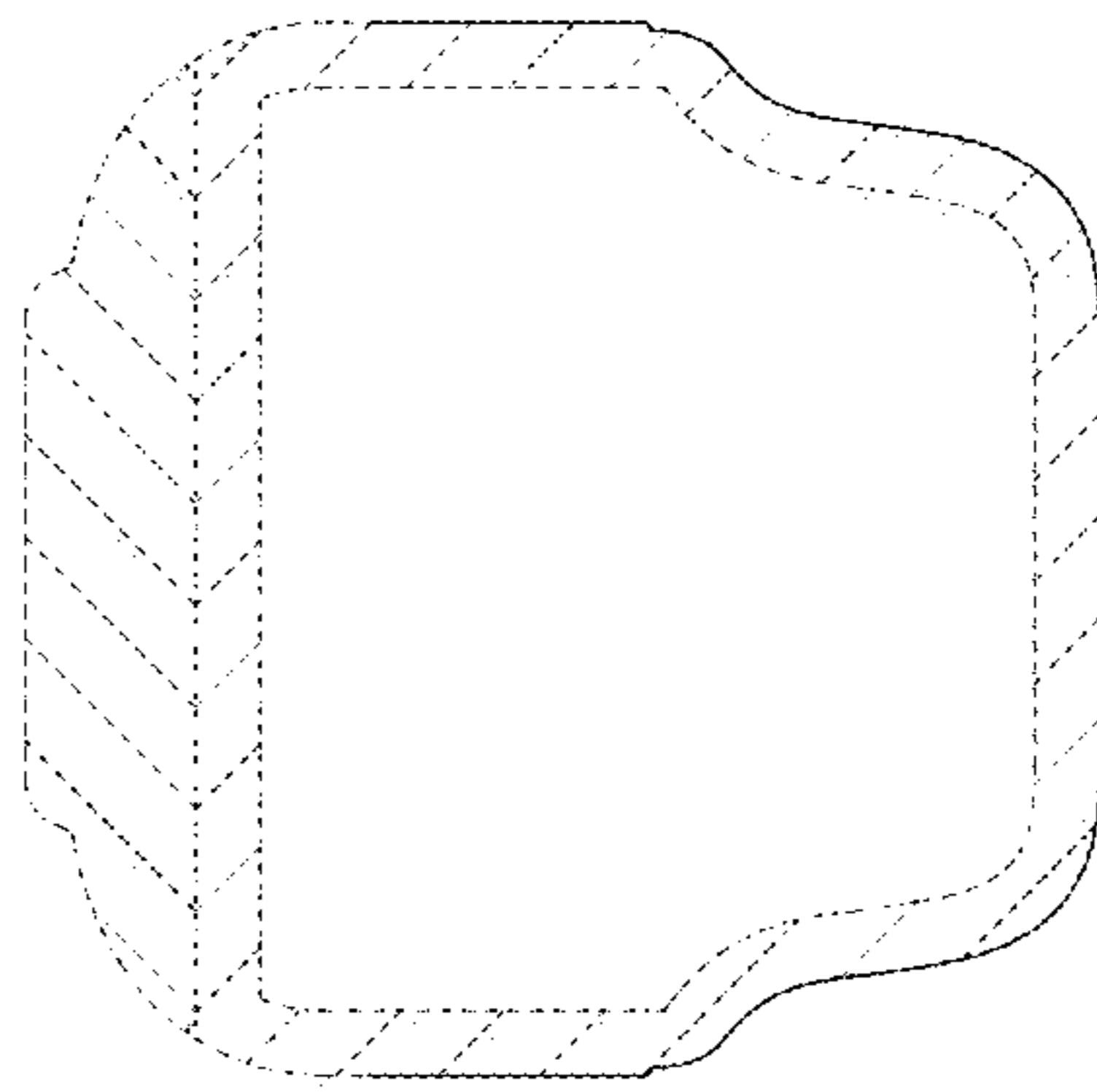


FIG.9

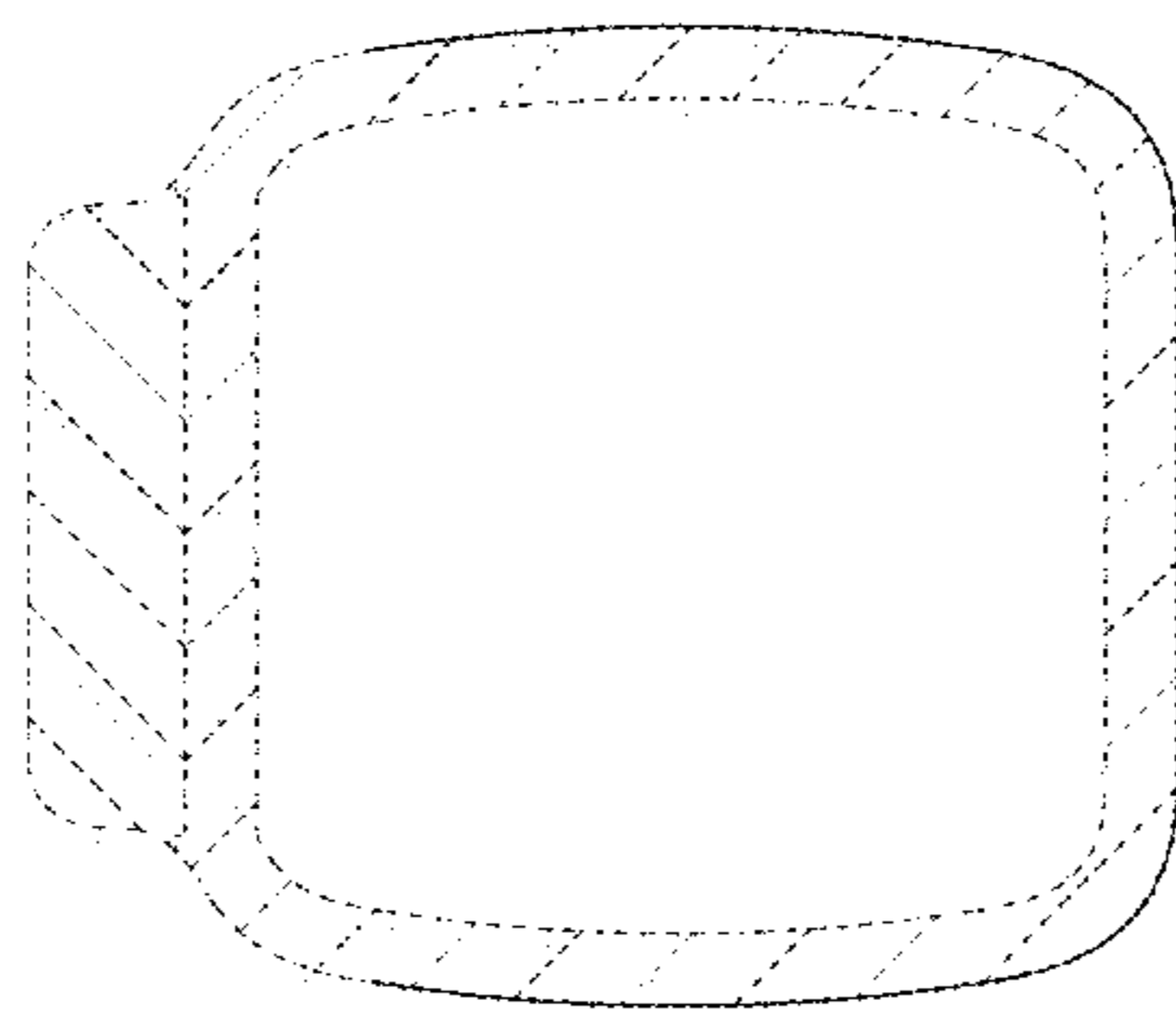




FIG.10

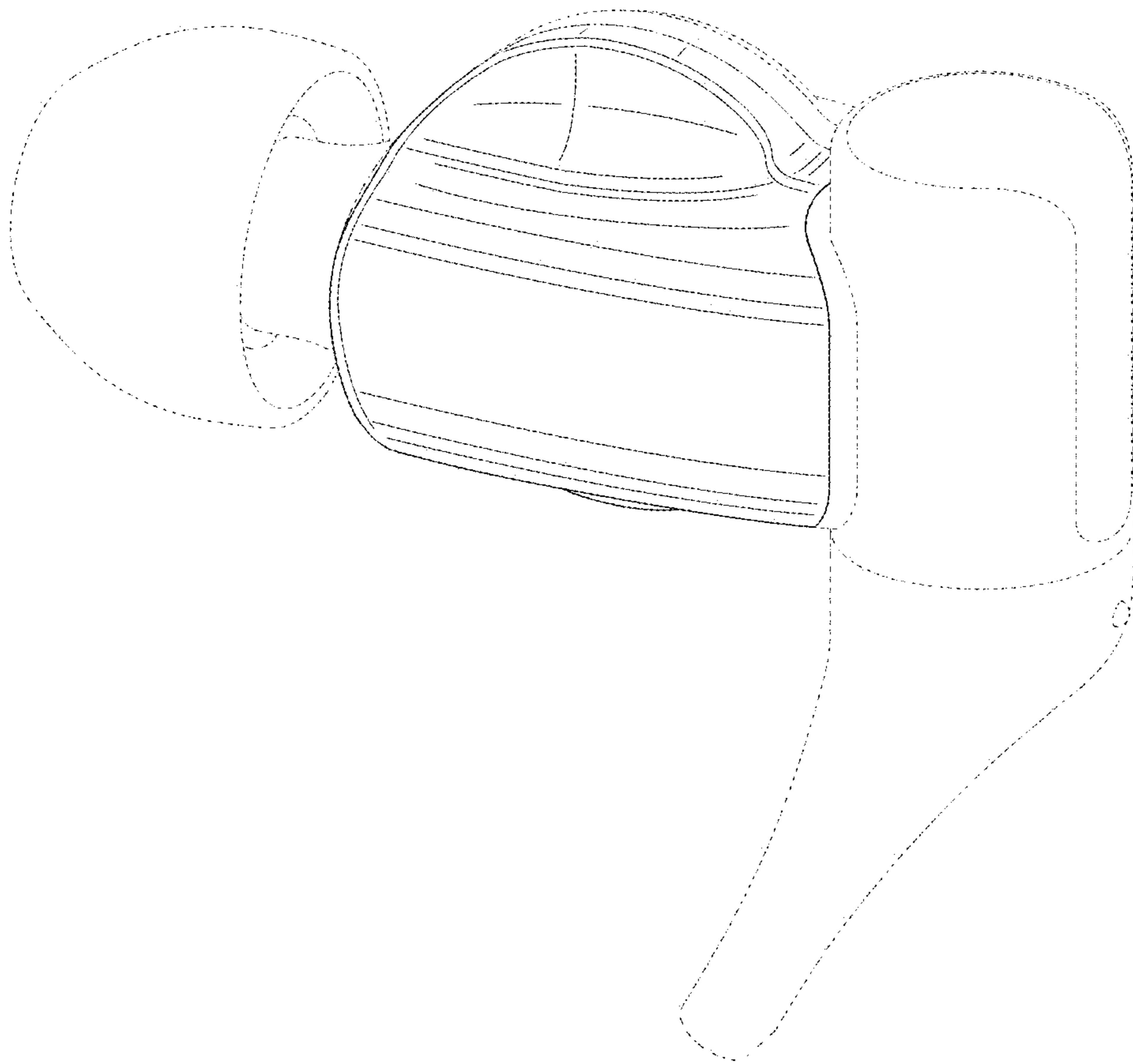


FIG.11

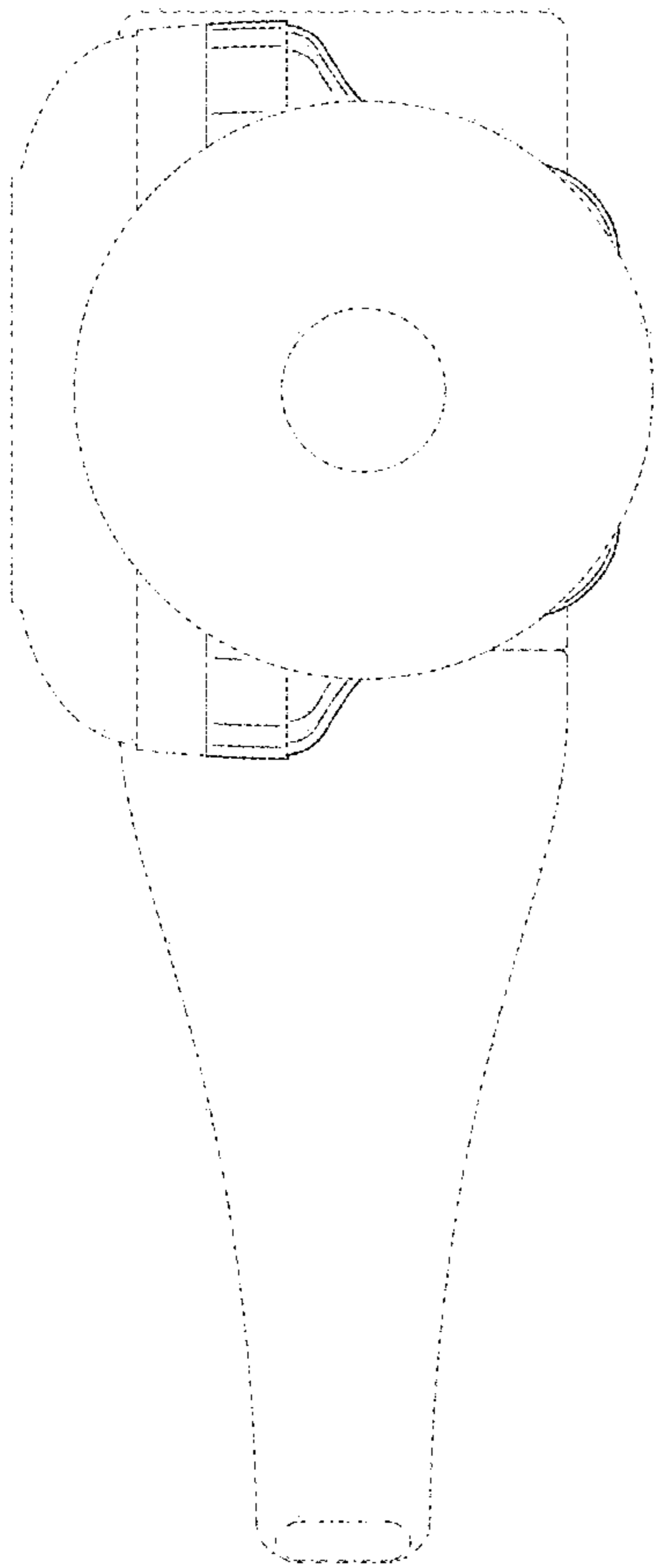


FIG.12

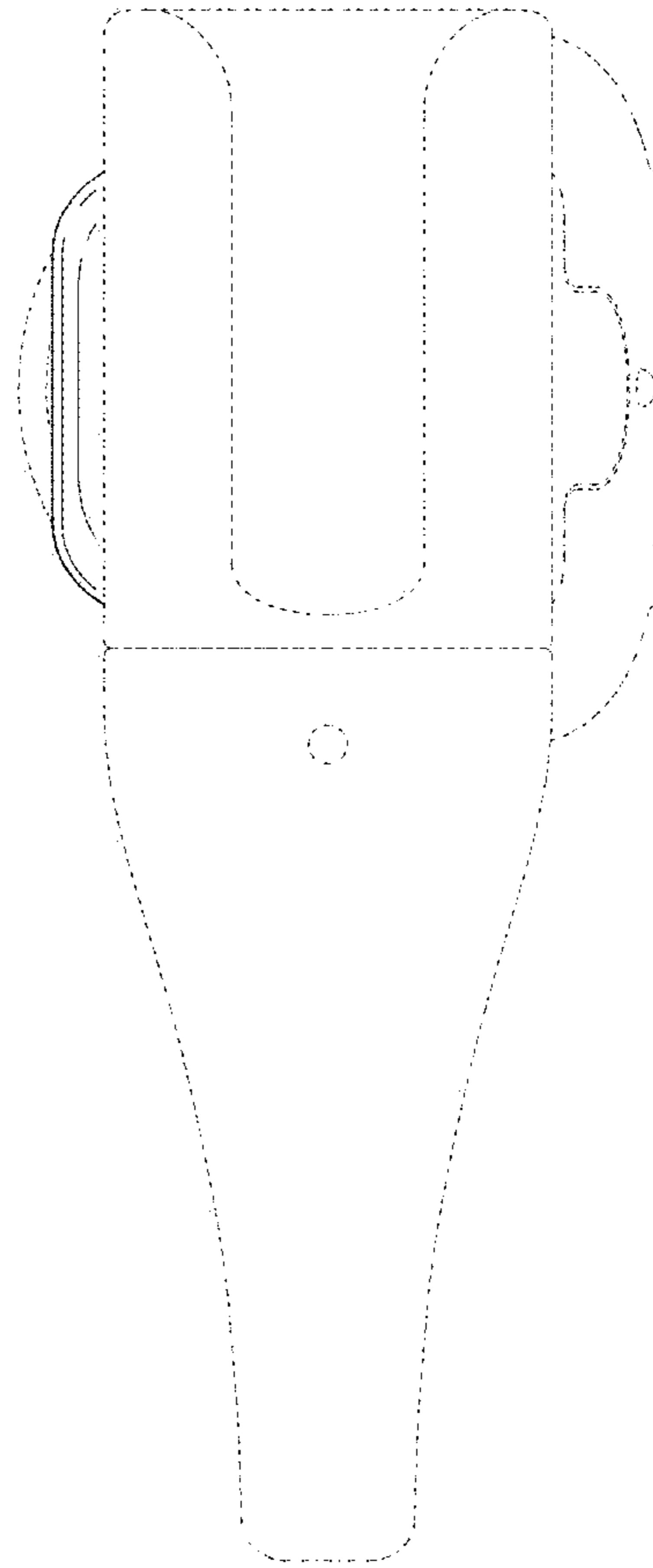


FIG.13

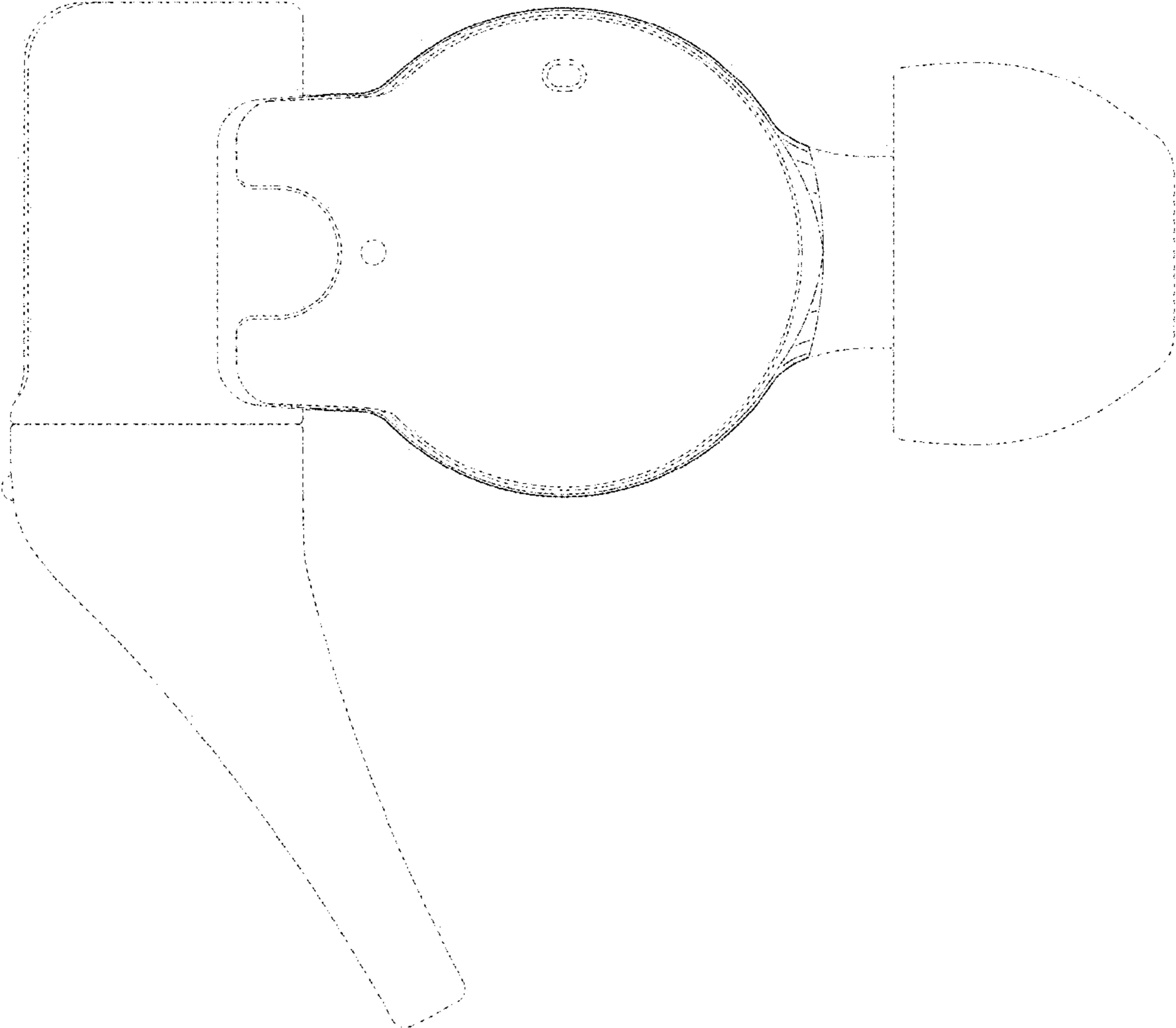


FIG. 14

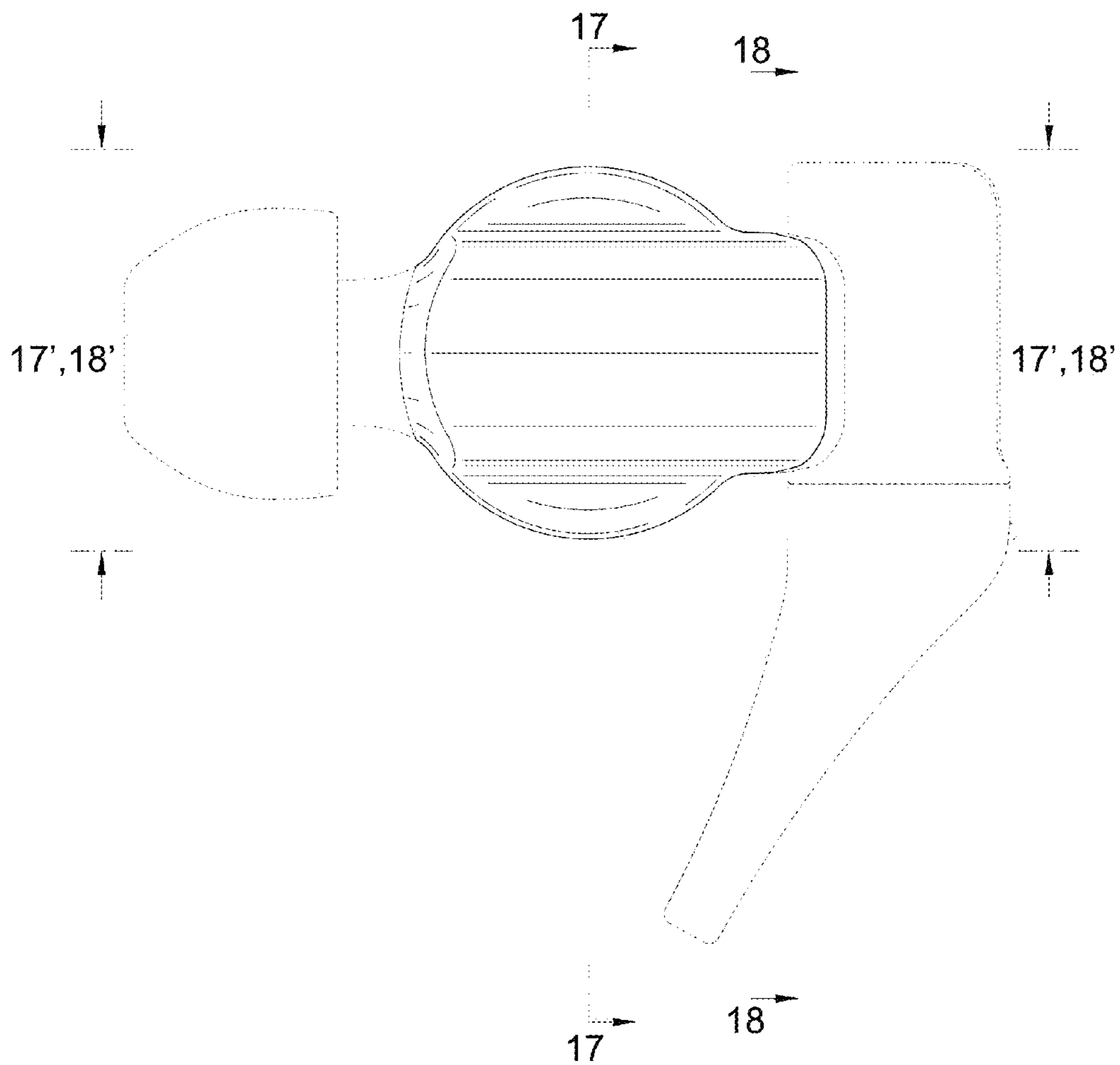


FIG.15

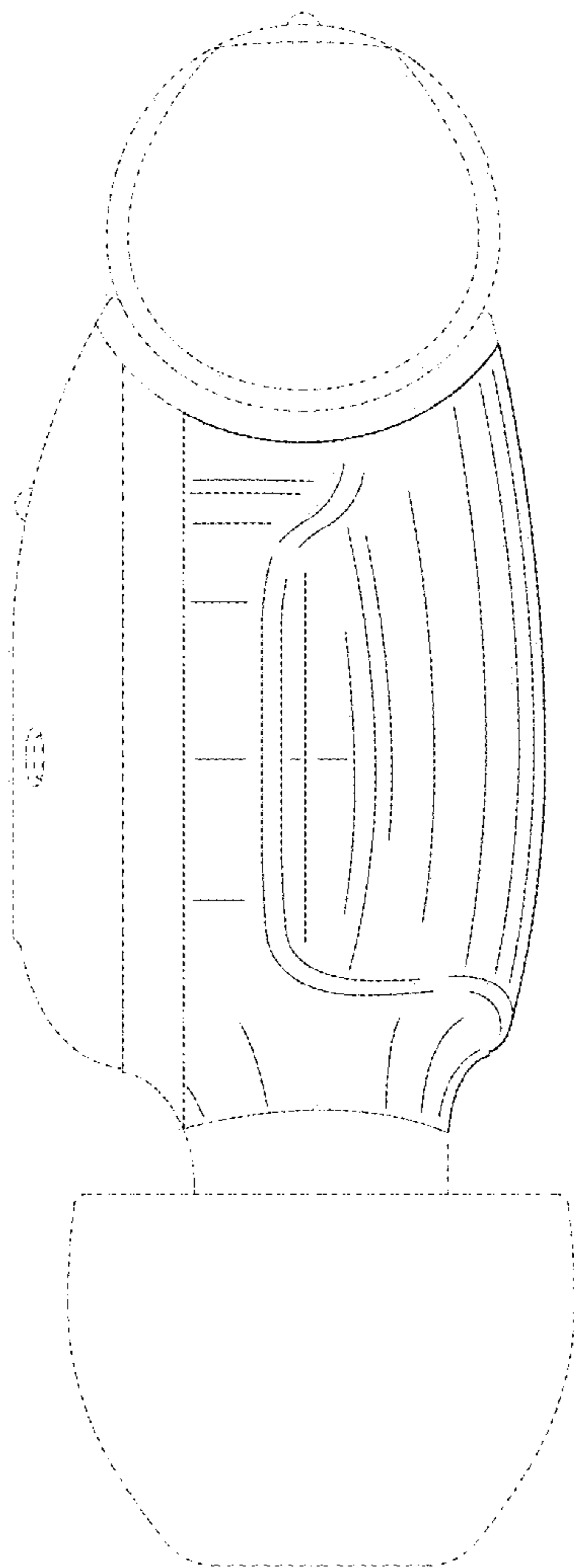


FIG.16

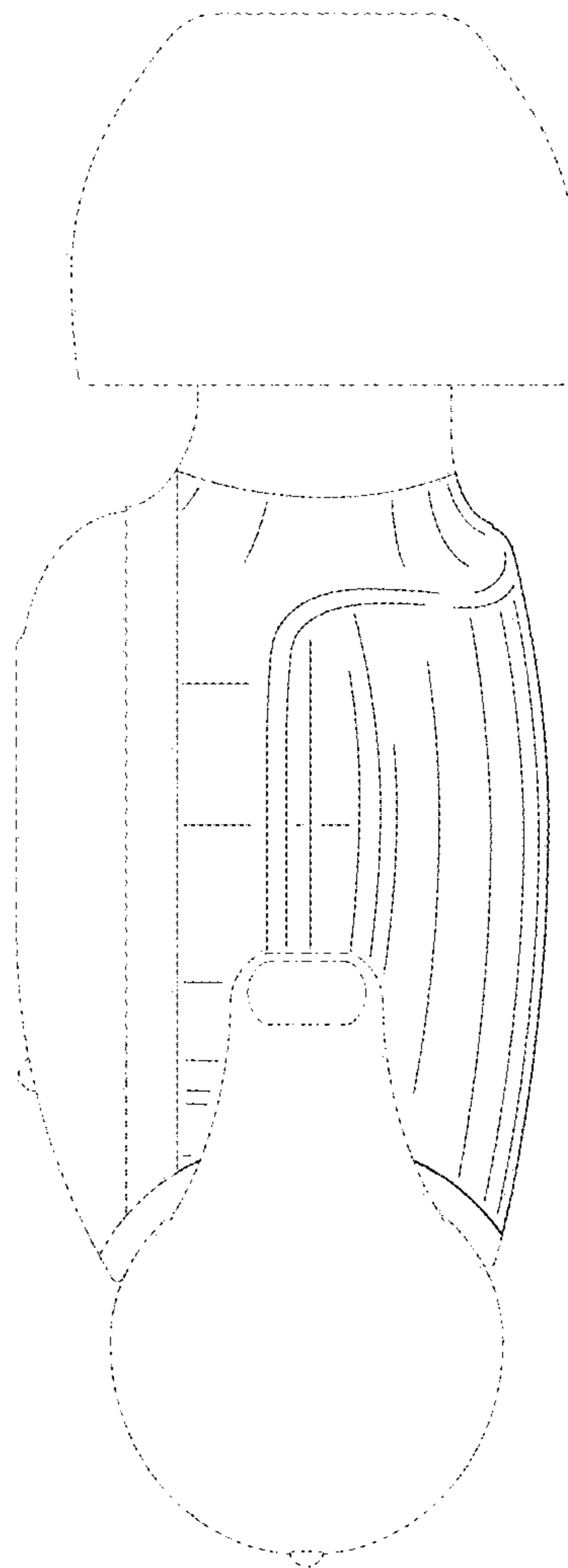


FIG.17

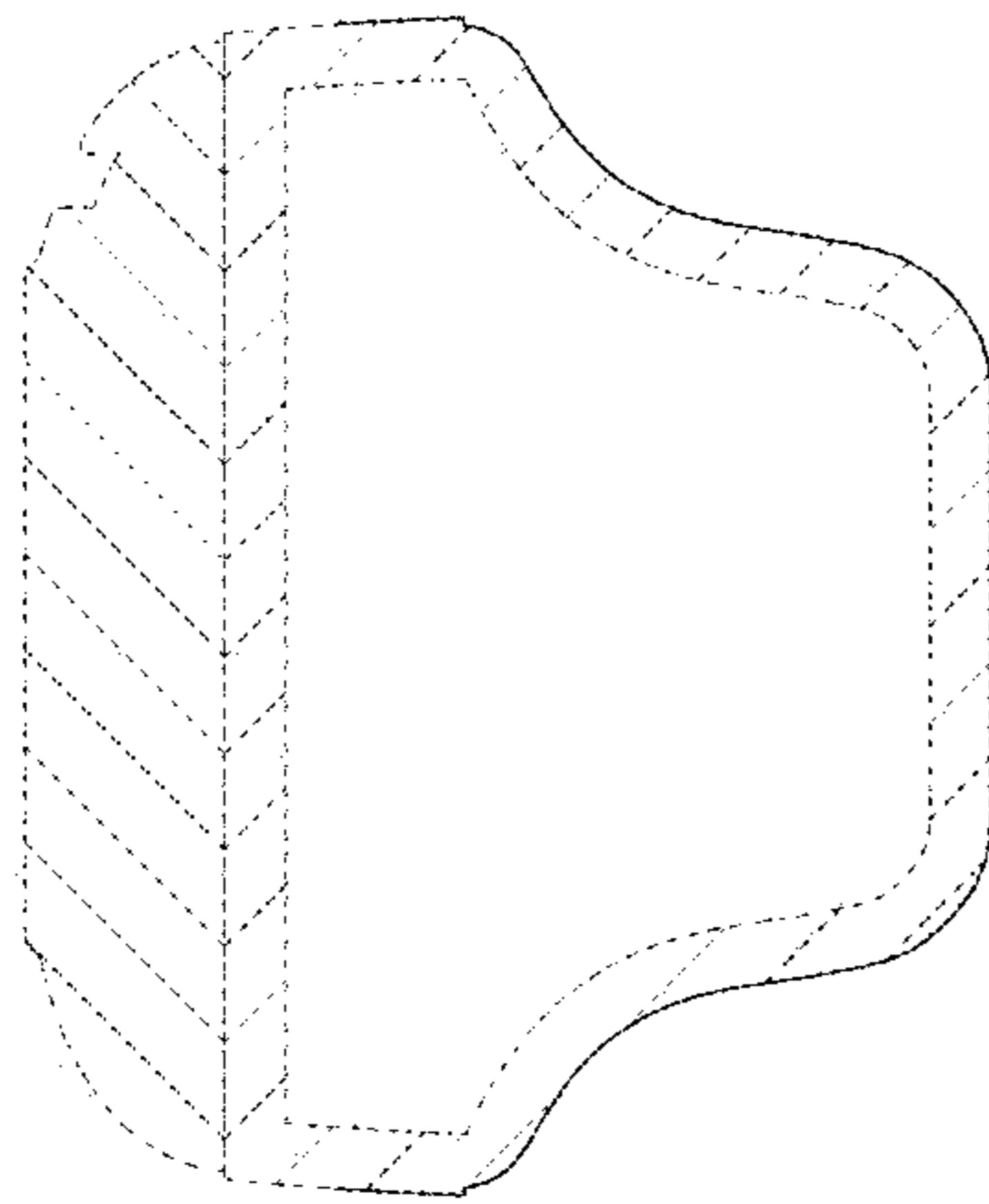


FIG.18

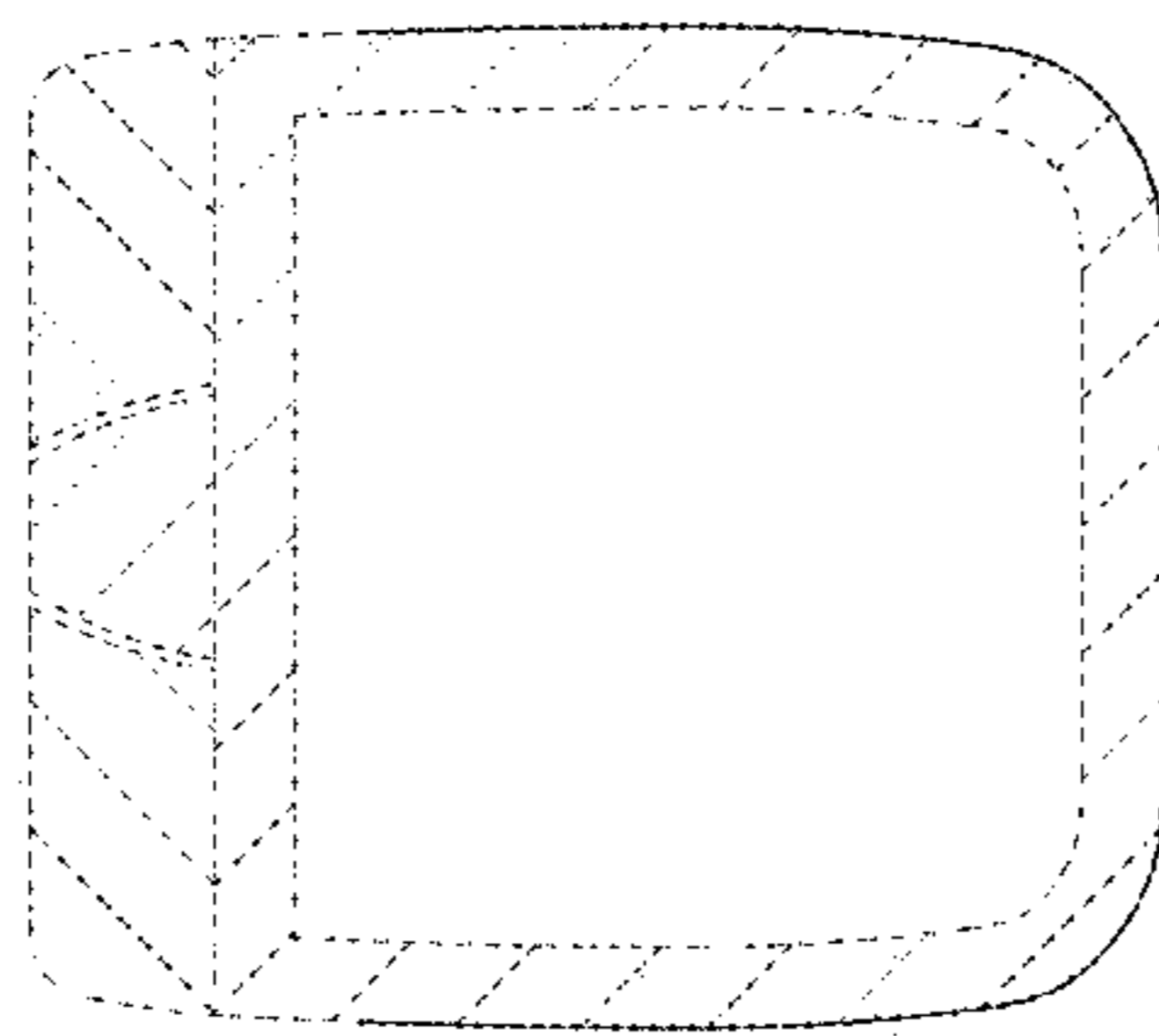


FIG. 19

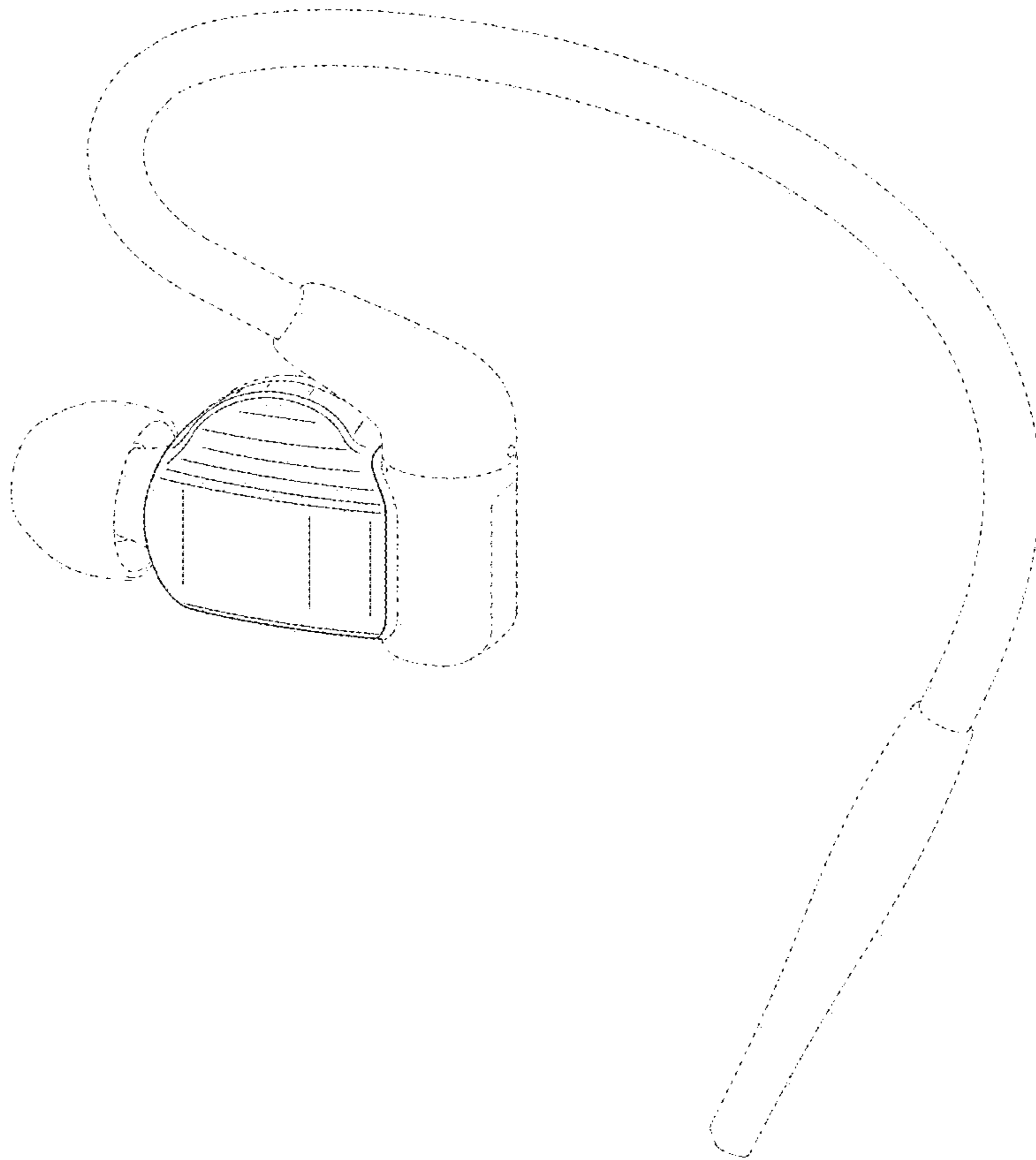


FIG.20

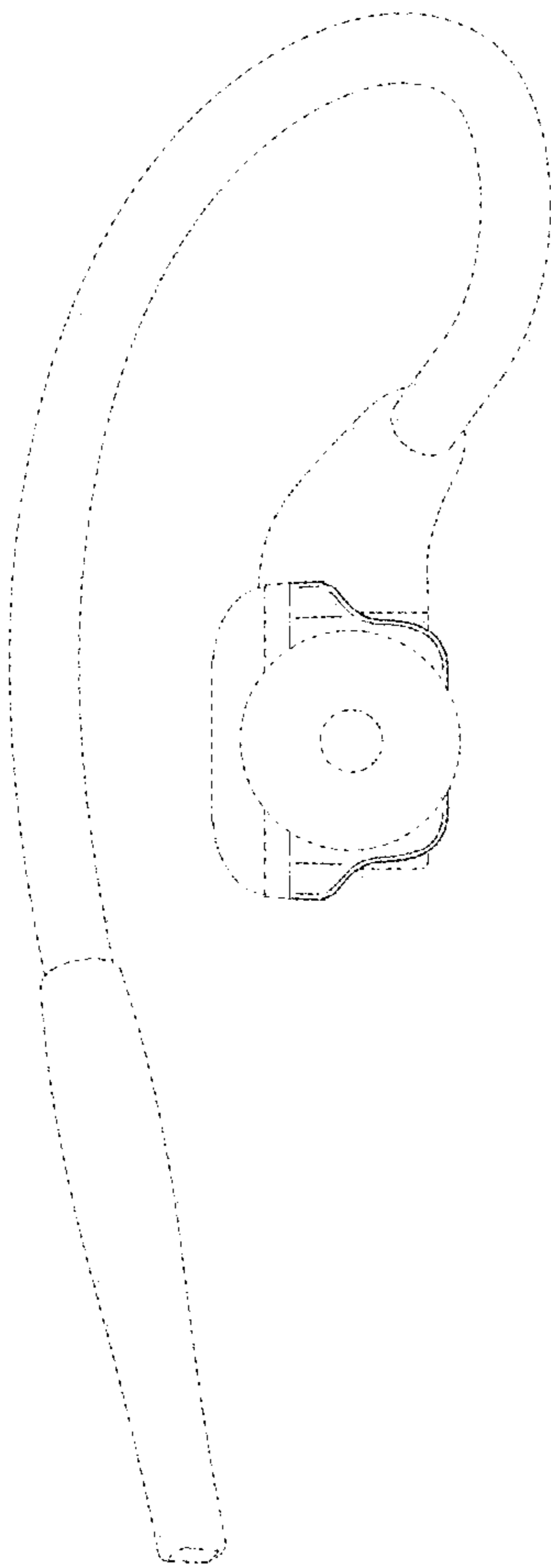


FIG.21

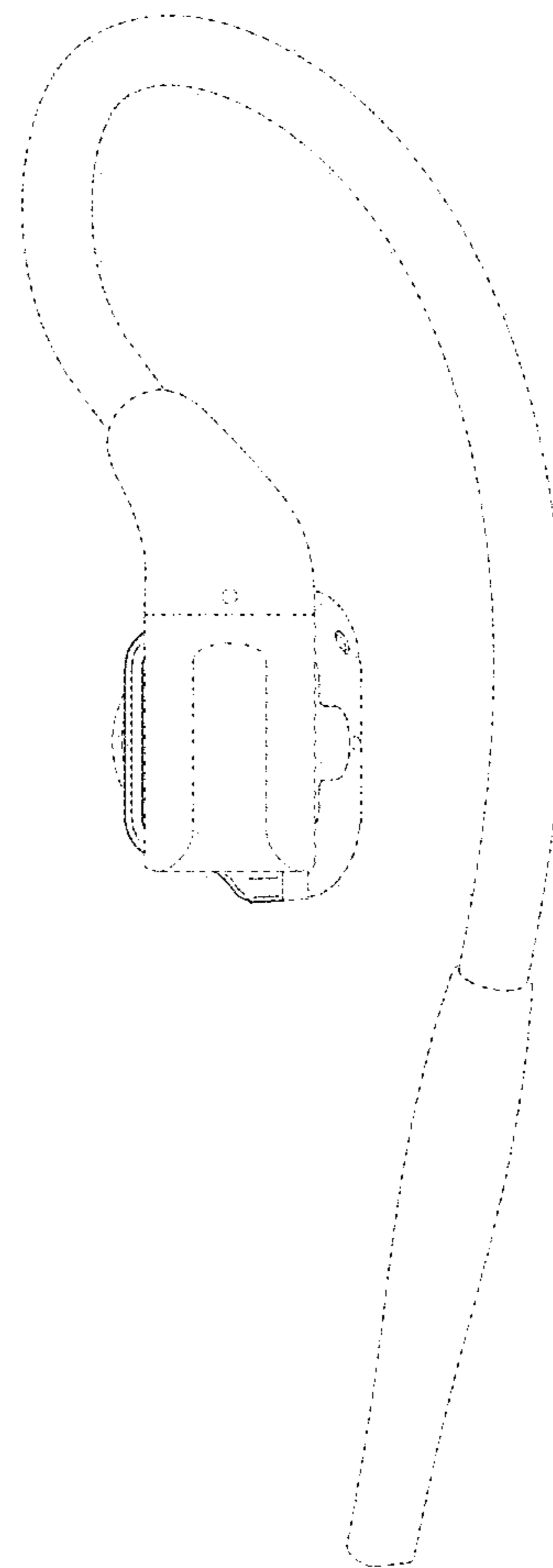




FIG.22

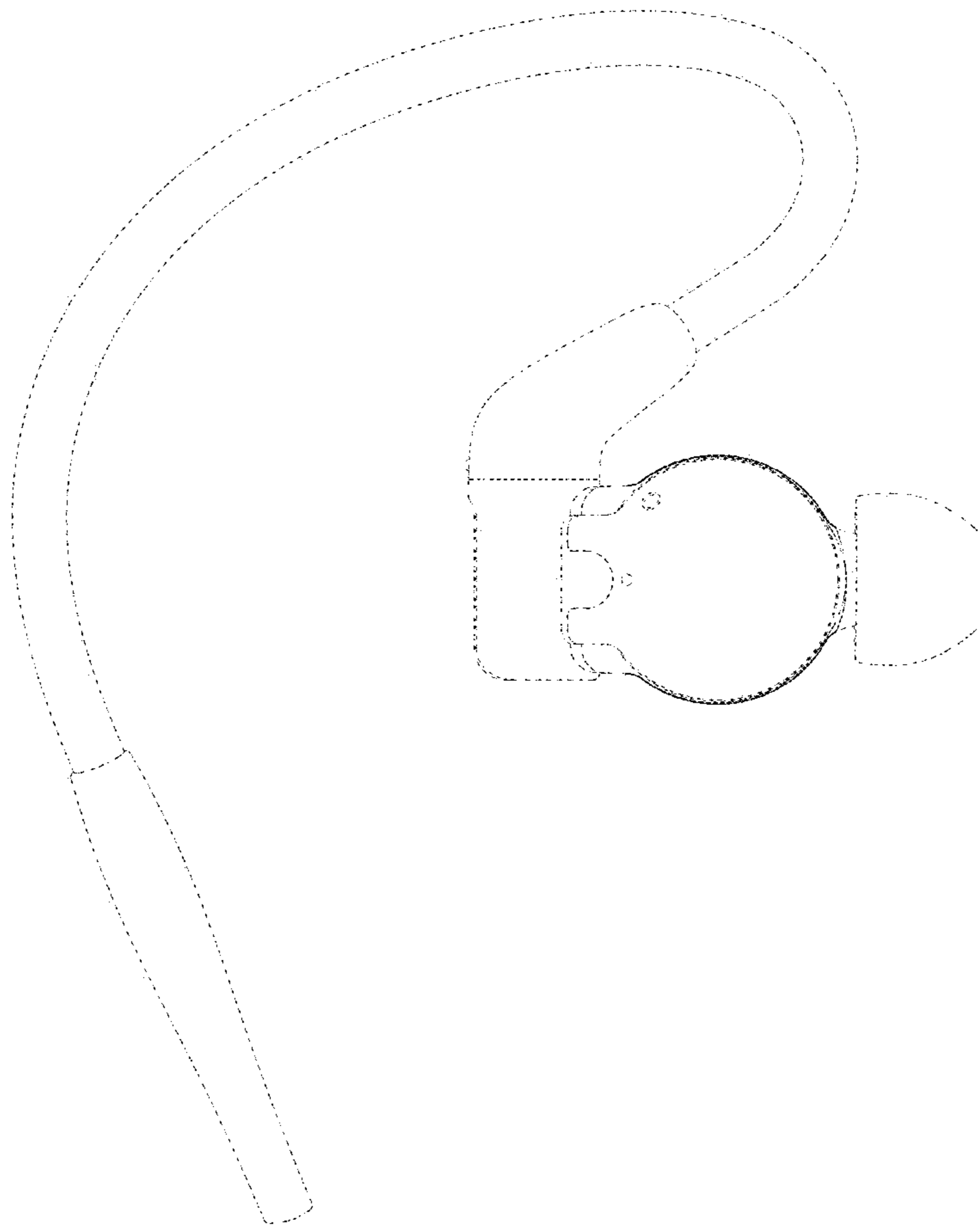


FIG.23

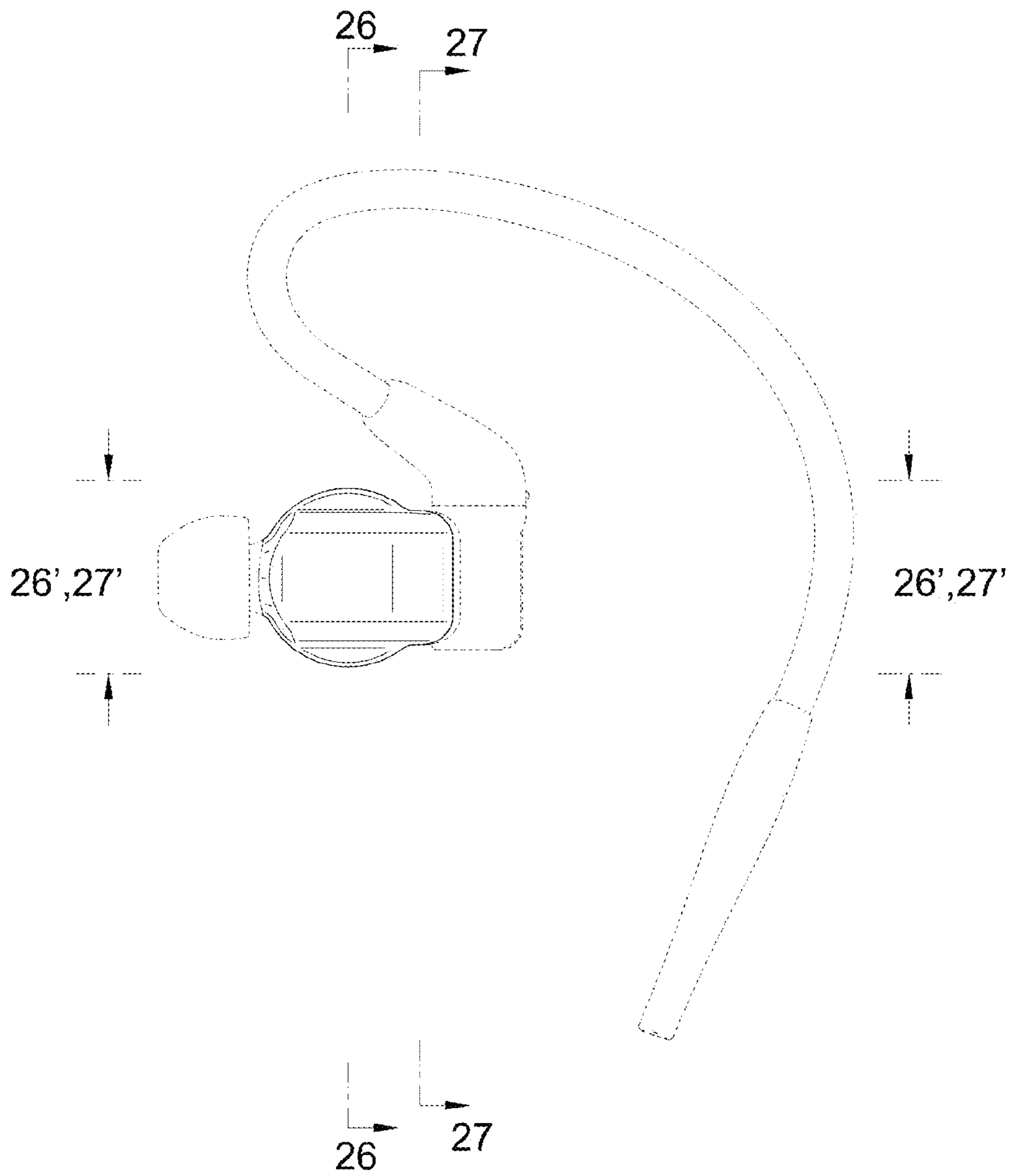


FIG.24

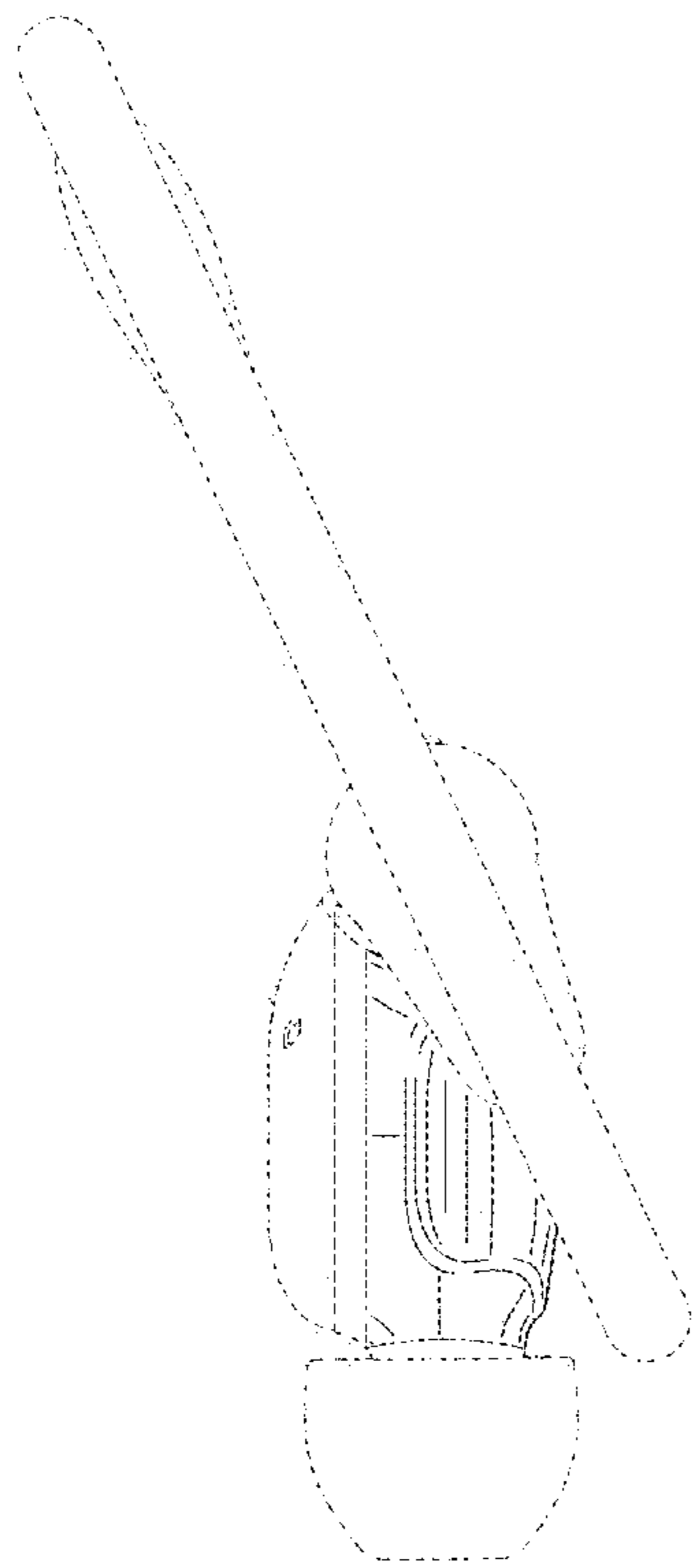


FIG.25

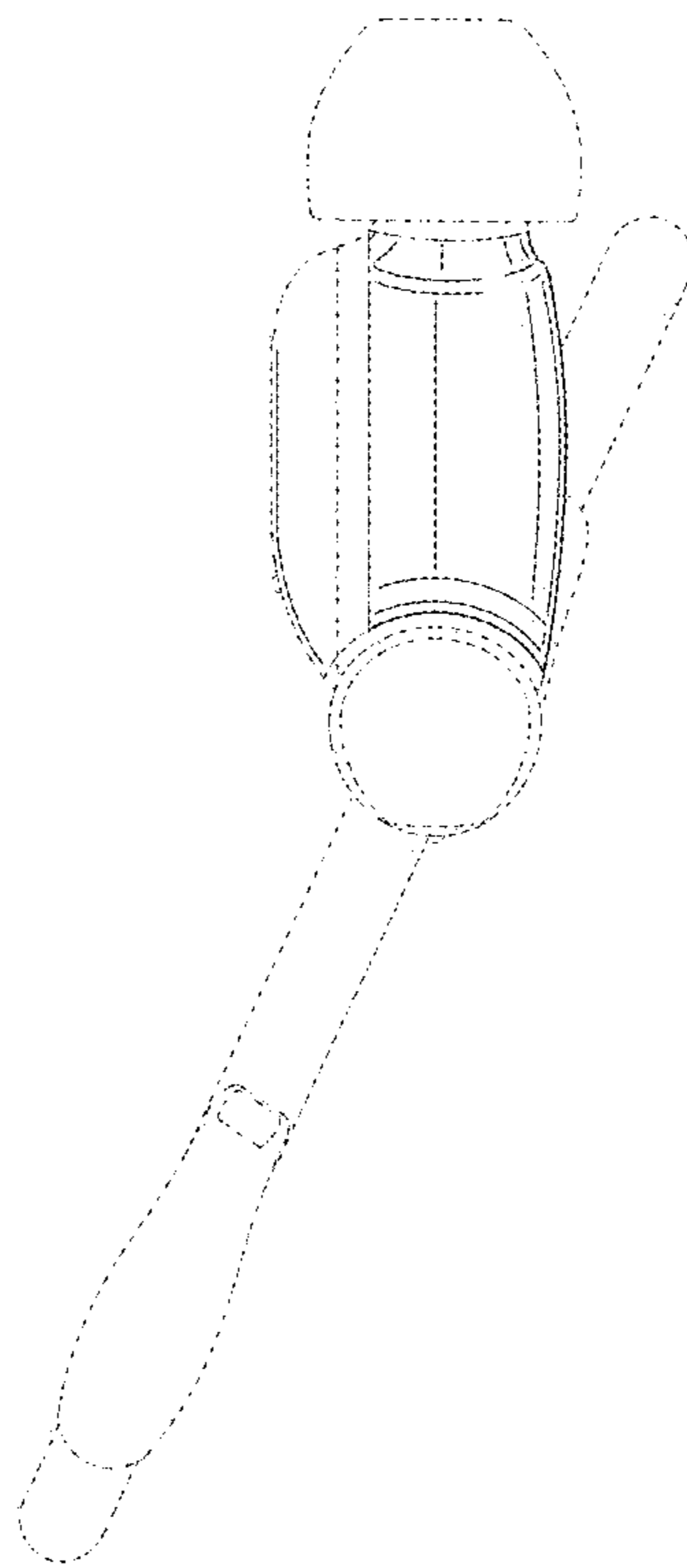


FIG.26

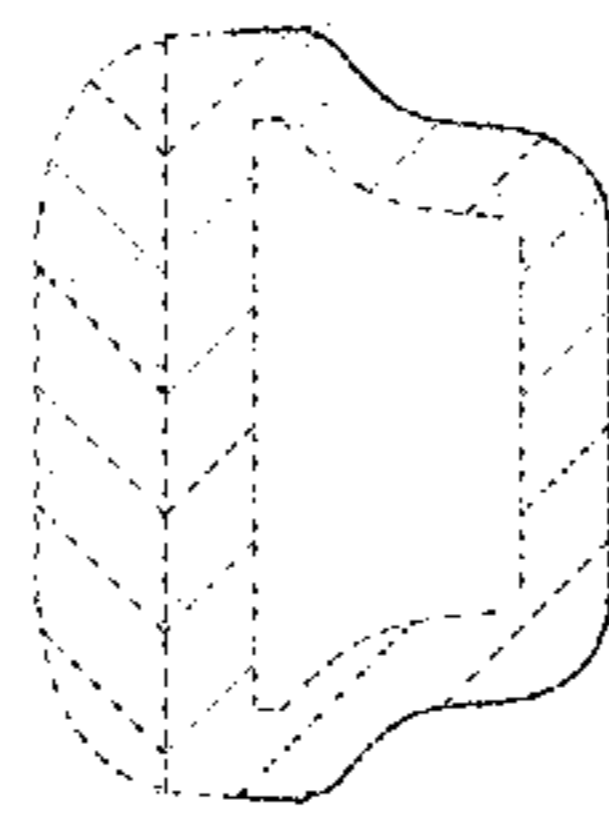


FIG.27

